

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	836	bevel\$3 near5 (die wafer IC chip)	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:13
L2	200	L1 and (polish\$3 etch\$3)	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:13
L3	22104	("v" near10 groove)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:14
L4	1583	L3 and etch\$3	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:06
L5	1295	L4 and (die wafer dice substrate)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:14
L6	1583	L4 and (polish\$3 etch\$3)	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:08
L8	1295	L5 and (polish\$3 etch\$3)	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:08

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L9	1583	5 6 8	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:09
L10	99	9 and edge	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:15
L11	0	10 and triangle	FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/03/04 22:09
L12	4018	bevel\$3 near5 (die wafer IC chip)	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:13
L13	1232	12 and (polish\$3 etch\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:13
L14	63757	("v" near10 groove)	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:14
L15	112	14 and 13	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:14
L16	100	15 and (die wafer dice substrate)	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:14
L17	93	16 and edge	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/04 22:15